

ALPHA[®] OM-362

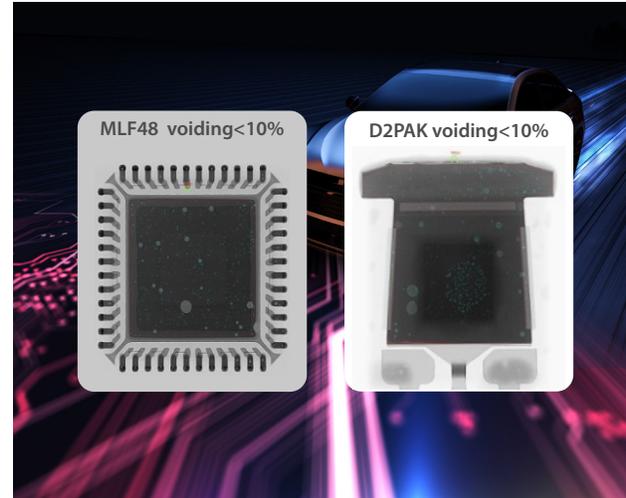
Ultra-Low Voiding, High-Reliability Solder Paste

ALPHA OM-362 is a lead-free, zero-halogen, no-clean solder paste available in T4 powder. It is designed to provide ultra-low voiding performance on all component types including bottom terminated components.

ALPHA OM-362 achieves IPC Class III voiding on BGA components averaging less than 10% voiding on Bottom Terminated Components (BTC). This paste is designed for ultra-low voiding performance with high reliability alloys such as Innolot as well as traditional SAC alloys.

KEY ATTRIBUTES

- **Ultra-Low Voiding Performance:** Enables increased process stability, and enhances thermal and electrical performance of the most demanding component applications.
- **Excellent Electromigration Characteristics:** Passes J-STD-004C IPC-TM-650 at 200µm to ensure electrical reliability & functionality of fine-pitched components.
- **Wide Reflow Profile Window:** Enables high quality solderability of complicated, high density PCB assemblies using straight ramp and soak profiles, as high as 150° to 200°C soak.
- **Good Coalescence and Wetting Performance:** Coalesces down to 180µm exhibiting good wetting characteristics and solder joint reliability.
- **Excellent Solder Joint and Flux Residue Cosmetics:** Easily penetrable and clear flux residue enables good probe contact during quality inspection.
- **Zero-Halogen, No Halogens Intentionally Added:** Ensures RoHS compliance for a safe and environmentally friendly assembly process.



macdermidalpha.com

MacDermid Alpha 
ELECTRONICS SOLUTIONS

Alpha is a product brand of MacDermid Alpha Electronics Solutions. © 2023 MacDermid, Inc. and its group of companies. All rights reserved. "R" and "TM" are registered trademarks or trademarks of MacDermid, Inc. and its group of companies in the United States and/or other countries.